Most Powerful IPM on the Market

SKiiP® 4
500kW up to 2.1MW
Sinter technology
- 5% improvement in total thermal resistance thanks to sinter layer
- Unbreakable joint between chips and DCB
- High melting point at > 900°C (4 x higher than standard solder) no solder fatigue

IGBT 4 and CAL4F technology
- \( V_{th, \text{max}} = 175°C \), the key to higher current capability

**Extremely high power cycling capability**

![Graph showing power cycling performance](image)

**Superior reliability**

New pressure contact design
- Low-inductive design
- More homogeneous current distribution

Robust mechanical design
- High ruggedness against mechanical shock and vibration

Advanced driver design
- Enhanced FIT rate thanks to ASIC technology
- Switching and sensor signals safety isolated

**Benefits of SKiiP 4 driver**

Function and self-protection
- Digital signal transmission for high signal integrity and noise immunity
- All switching and sensor signals safety isolated
- New 1500Vdc version for typical PV-solar power applications
- Parallel operation for increased output power

SKiiP 4 product range
- 1200V / 1700V SKiiP 4

**Key features**

- 500KW up to 2.1MW
- 3 in 1: driver with protection functions, semiconductors & cooling
- Integrated current, voltage and temperature sensor
- Sintered chips, no solder fatigue
- High power cycling capability
- SKiiP technology / Single-sided sintering technology

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NOTE: All information is based on our present knowledge and is to be used for information purposes only. The specifications of our components may not be considered as an assurance of component characteristics.